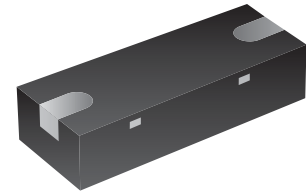




Product Change Notification

CHIP DIODES

Bourns Rep District Sales Managers
Bourns Rep Distributor Managers
Corporate Distributor Product Managers
Americas Sales Team
Asia Sales Team
Europe Sales Team



April, 2009

Bourns Adds Backend Package Assembly Location for Diode Products

Bourns is adding an additional backend package assembly location for the assembly of our diode products. The Diode Product Line strategy is always to have two (2) qualified package assembly locations to help avoid any production line downtime and for continued delivery of product to our customers. Below is the affected Bourns part number that is currently package assembled in the Philippines.

Part Number [CDDFN2-T4.7C](#)

To increase backend package assembly capacity while reducing lead times, Bourns will add the second DFN-2 backend package assembly location in Taiwan for the above part number for continued secure supply chain management and delivery support to our customers.

Samples of the above part number using the second DFN-2 backend package assembly location in Taiwan are now available. Reliability data on units package assembled at the new location is now available on request. Mass production using the second DFN-2 backend package assembly location in Taiwan has been available since February 1, 2009.

Bourns is issuing 90 days notice that mass production at the alternative backend package assembly location will start June 30, 2009.